

ABSTRACT

A surface mount electrical component free from falling off a substrate when the substrate is inverted and subjected to reflow without requiring investment for additional soldering equipment.

- 5 The total circumferential length (B) of a second soldering portion (P2) is set such that, when the component is on the underside of the circuit board (100), the relationship between a downward rotational moment (M1) around the first soldering portion (P1) caused by the gravity force, and an upward rotational moment (M2) acting
- 10 on the second soldering portion (P2) produced by the surface tension of melted solder melted during overall-heating soldering is $M1 \leq M2$; and the total circumferential length (A) of a first soldering portion (P1) is set such that, when the component is on the underside of the circuit board (100), the relationship between a downward
- 15 rotational moment (M3) around the second soldering portion (P2) caused by the gravity force and an upward rotational moment (M4) acting on the first soldering portion (P1) produced by the surface tension of melted solder melted during the overall-heating soldering is $M3 \leq M4$.